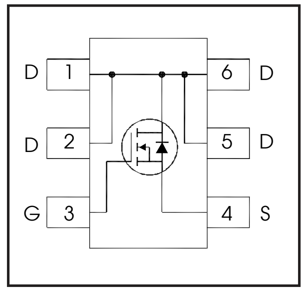
International Rectifier

IRLTS6342PbF

HEXFET® Power MOSFET

V_{DS}	30	V
V_{GS}	±12	V
$R_{DS(on)}$ max (@V_{GS} = 4.5V)	17.5	mΩ
$R_{DS(on)}$ max (@V_{GS} = 2.5V)	22.0	mΩ
Q_g (typical)	11	nC
I_D (@T_A = 25°C)	8.3	A



TSOP-6

Applications

- System/Load Switch

Features and Benefits

Features		Resulting Benefits
Industry-Standard TSOP-6 Package		Multi-Vendor Compatibility
RoHS Compliant Containing no Lead, no Bromide and no Halogen	⇒	Environmentally Friendlier
MSL1, Consumer Qualification		Increased Reliability

Orderable part number	Package Type	Standard Pack		Note
		Form	Quantity	
IRLTS6342TRPBF	TSOP-6	Tape and Reel	3000	

Absolute Maximum Ratings

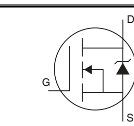
	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	±12	
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 4.5V	8.3	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 4.5V	6.7	
I_{DM}	Pulsed Drain Current ①	64	
P_D @T_A = 25°C	Power Dissipation ③	2.0	W
P_D @T_A = 70°C	Power Dissipation ③	1.3	
	Linear Derating Factor	0.02	W/°C
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C

Notes ① through ④ are on page 2

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	—	—	V	V_{GS} = 0V, I_D = 250μA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	23	—	mV/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	14.0	17.5	mΩ	V_{GS} = 4.5V, I_D = 8.3A ②
		—	17.5	22.0		V_{GS} = 2.5V, I_D = 6.7A ②
$V_{GS(th)}$	Gate Threshold Voltage	0.5	—	1.1	V	V_{DS} = V_{GS}, I_D = 10μA
$\Delta V_{GS(th)}$	Gate Threshold Voltage Coefficient	—	-4.3	—	mV/°C	
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	V_{DS} = 24V, V_{GS} = 0V
		—	—	150		V_{DS} = 24V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V_{GS} = 12V
	Gate-to-Source Reverse Leakage	—	—	-100		V_{GS} = -12V
gfs	Forward Transconductance	25	—	—	S	V_{DS} = 10V, I_D = 6.4A
Q_g	Total Gate Charge	—	11	—	nC	V_{GS} = 4.5V
Q_{gs}	Gate-to-Source Charge	—	0.5	—		V_{DS} = 15V
Q_{gd}	Gate-to-Drain Charge	—	4.6	—		I_D = 6.4A
R_G	Gate Resistance	—	2.2	—	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	5.4	—	ns	V_{DD} = 15V, V_{GS} = 4.5V ③
t_r	Rise Time	—	11	—		I_D = 6.4A
$t_{d(off)}$	Turn-Off Delay Time	—	32	—		R_G = 6.8Ω
t_f	Fall Time	—	15	—		See Figs. 18
C_{iss}	Input Capacitance	—	1010	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	96	—		V_{DS} = 25V
C_{rss}	Reverse Transfer Capacitance	—	70	—		f = 1.0MHz

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.0	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	64		
V_{SD}	Diode Forward Voltage	—	—	1.2	V	T_J = 25°C, I_S = 8.3A, V_{GS} = 0V ②
t_{rr}	Reverse Recovery Time	—	13	20	ns	T_J = 25°C, I_F = 6.4A, V_{DD} = 24V
Q_{rr}	Reverse Recovery Charge	—	5.8	8.7	nC	di/dt = 100/μs ②

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③	—	62.5	°C/W

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.
② Pulse width ≤ 400μs; duty cycle ≤ 2%.
③ When mounted on 1 ich square copper board.
④ R_θ is measured at T_J of approximately 90°C.

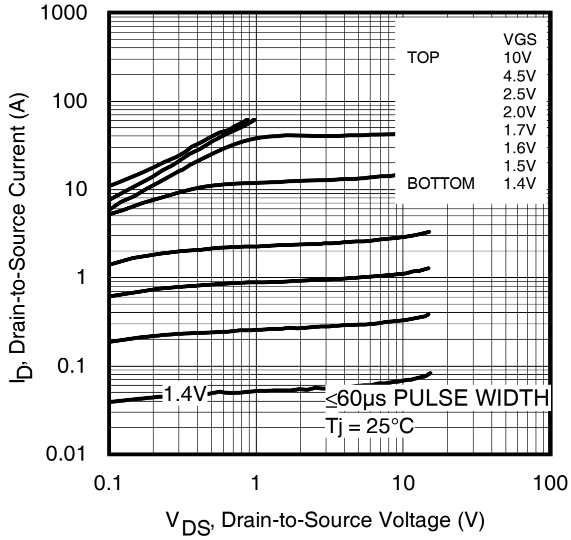


Fig 1. Typical Output Characteristics

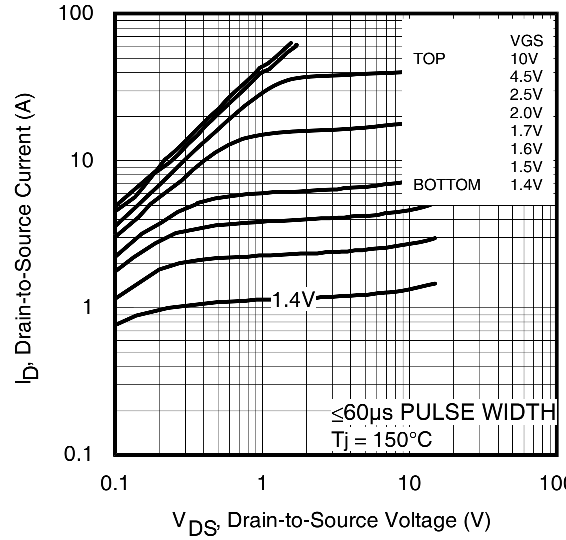


Fig 2. Typical Output Characteristics

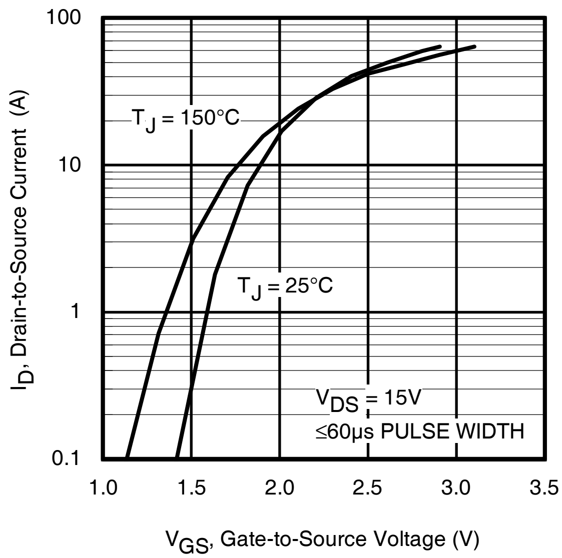


Fig 3. Typical Transfer Characteristics

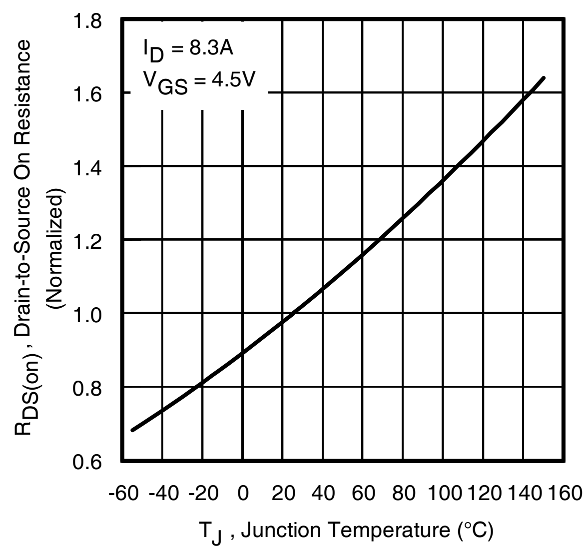


Fig 4. Normalized On-Resistance vs. Temperature

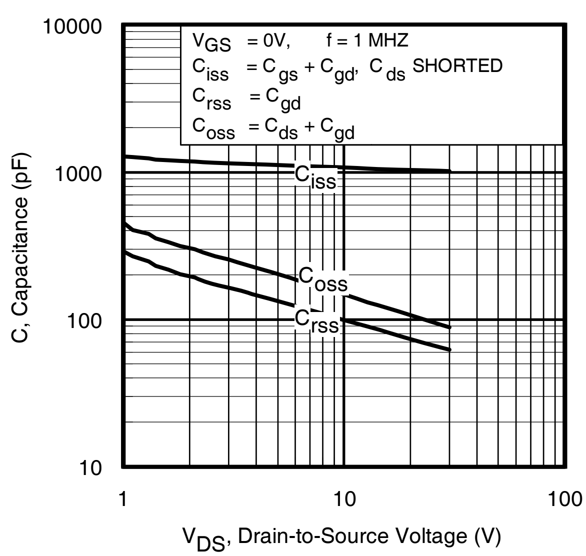


Fig 5. Typical Capacitance vs.Drain-to-Source Voltage

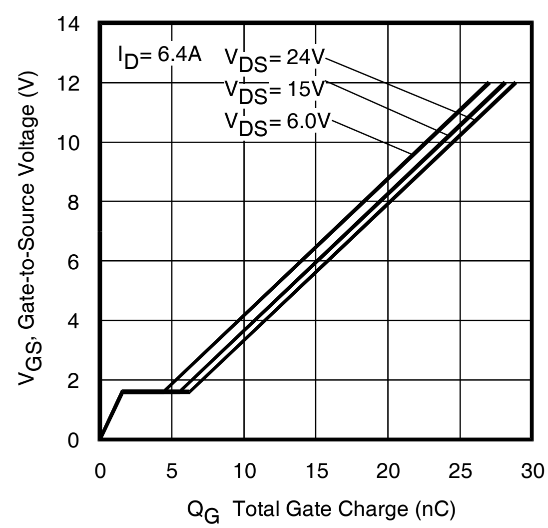


Fig 6. Typical Gate Charge vs.Gate-to-Source Voltage

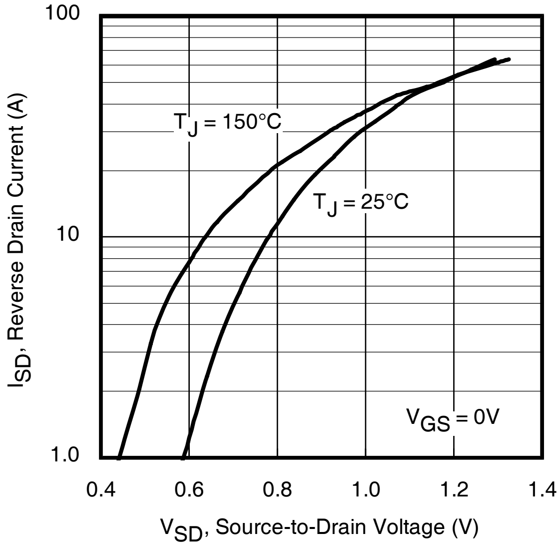


Fig 7. Typical Source-Drain Diode Forward Voltage

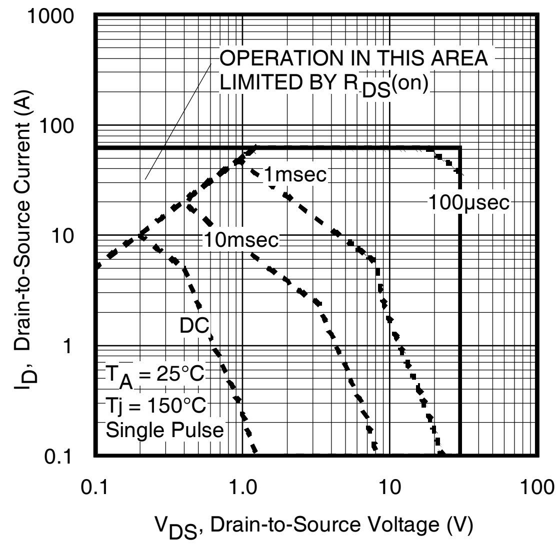


Fig 8. Maximum Safe Operating Area

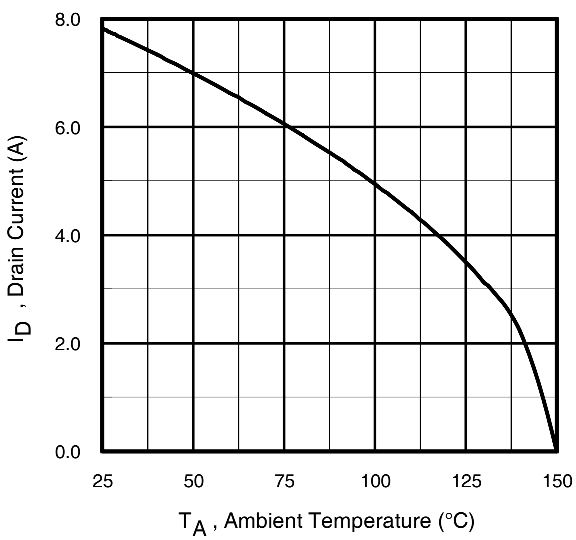


Fig 9. Maximum Drain Current vs. Ambient Temperature

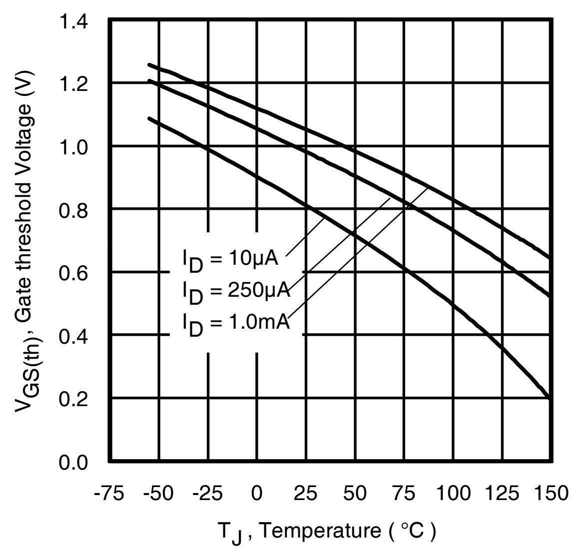


Fig 10. Threshold Voltage vs. Temperature

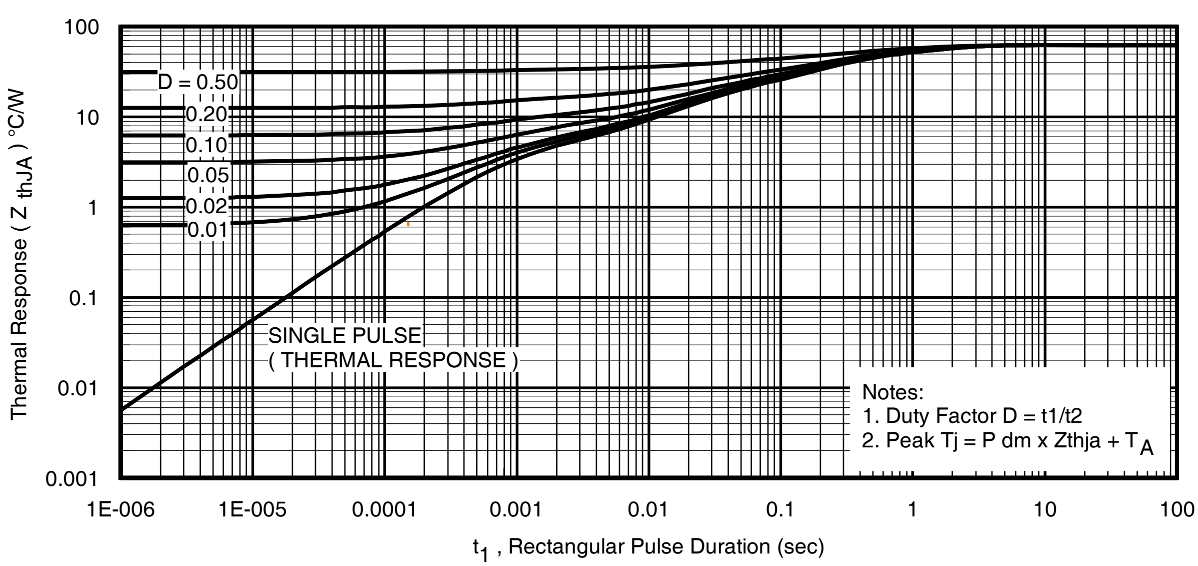


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

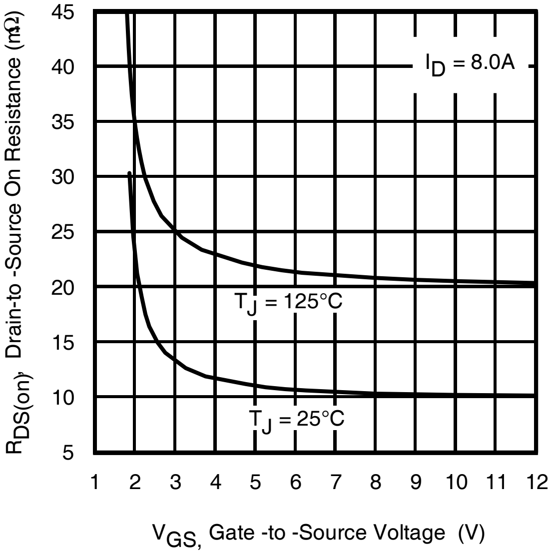


Fig 12. On-Resistance vs. Gate Voltage

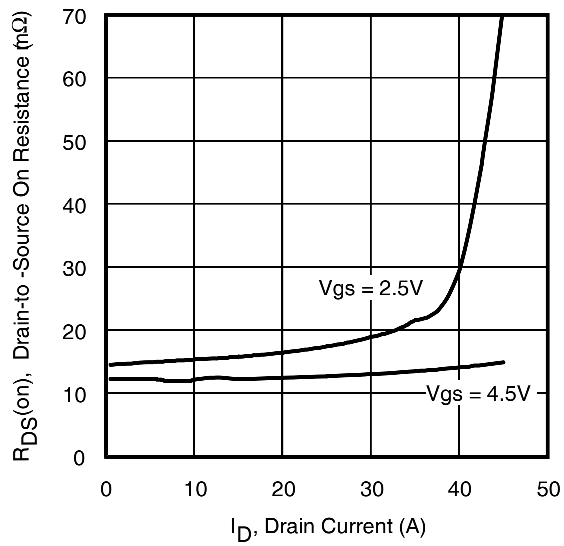


Fig 13. Typical On-Resistance vs. Drain Current

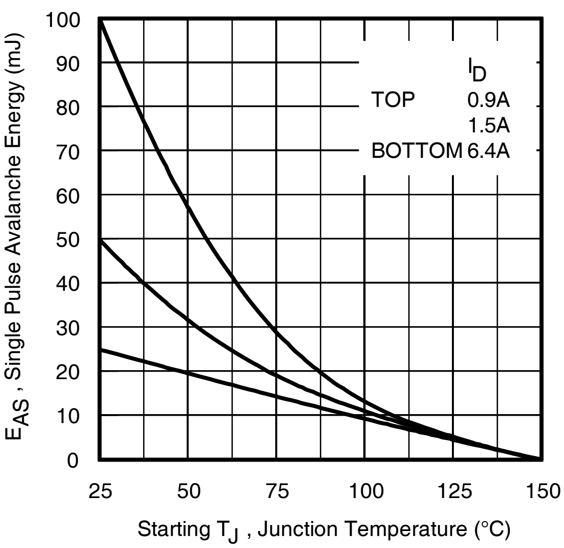


Fig 14. Maximum Avalanche Energy vs. Drain Current

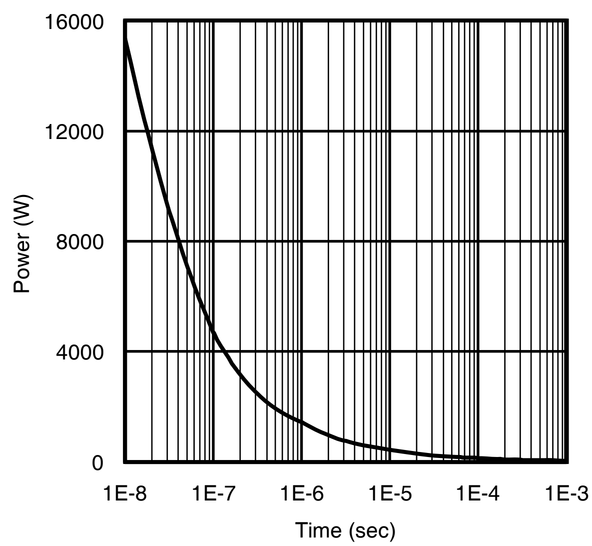


Fig 15. Typical Power vs. Time

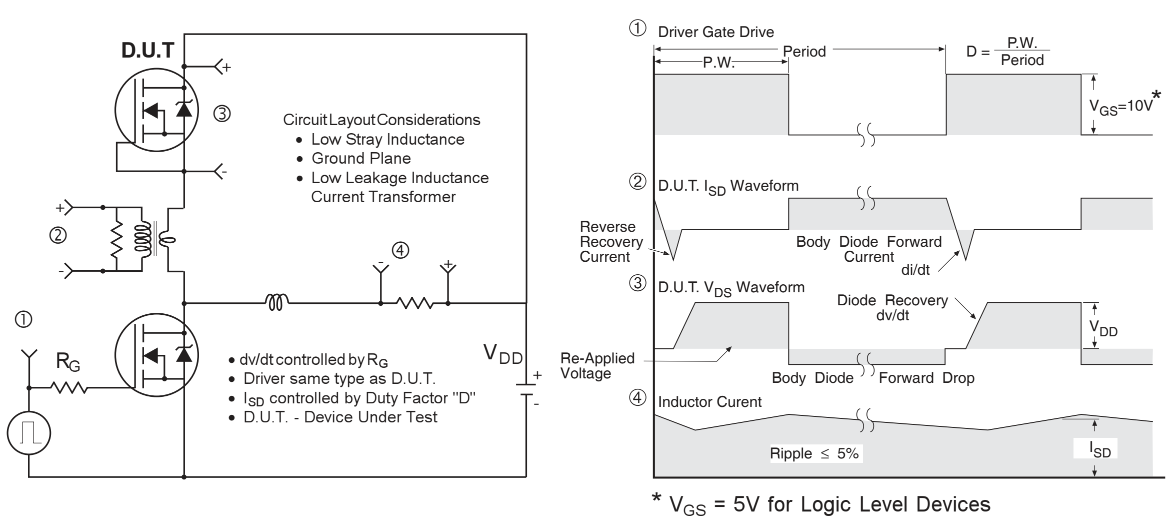


Fig 16. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

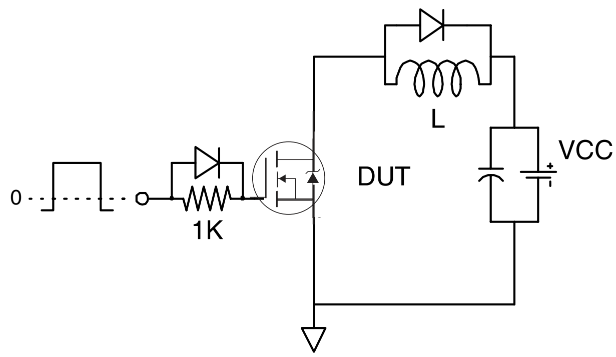


Fig 17a. Gate Charge Test Circuit

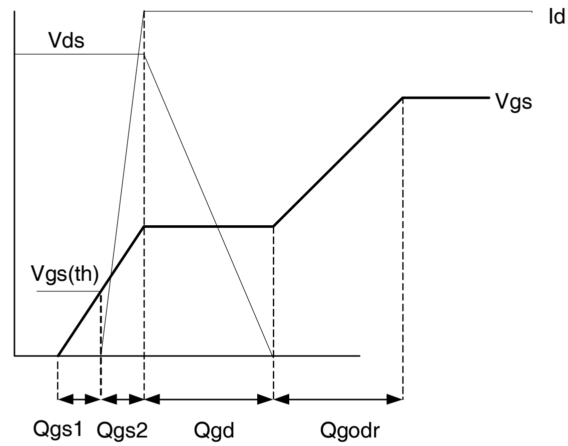


Fig 17b. Gate Charge Waveform

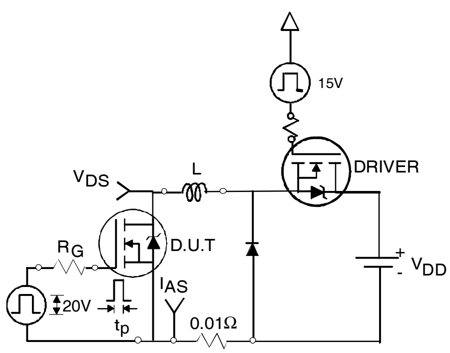


Fig 18a. Unclamped Inductive Test Circuit

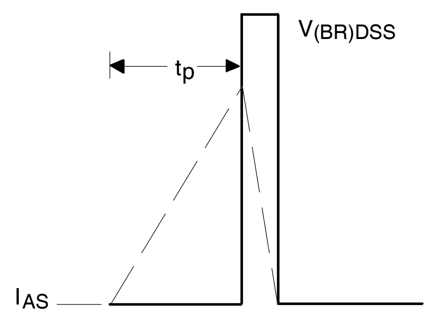


Fig 18b. Unclamped Inductive Waveforms

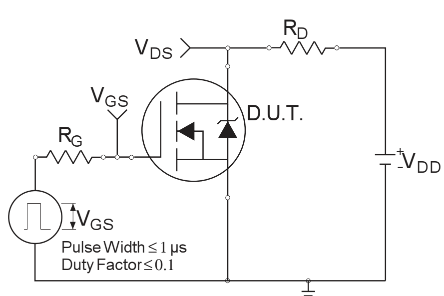


Fig 19a. Switching Time Test Circuit

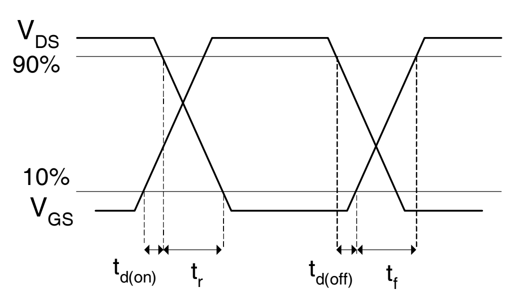
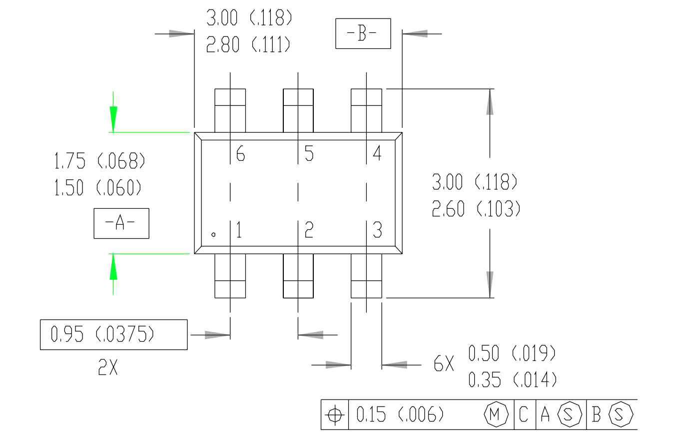
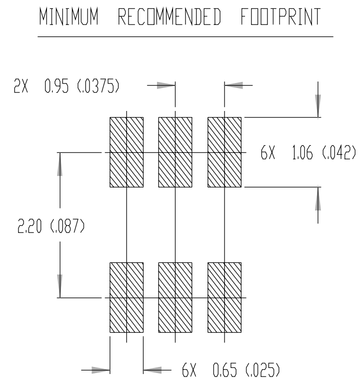
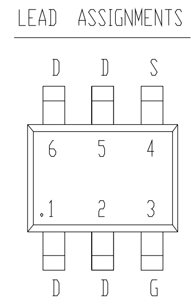


Fig 19b. Switching Time Waveforms

TSOP-6 Package Outline

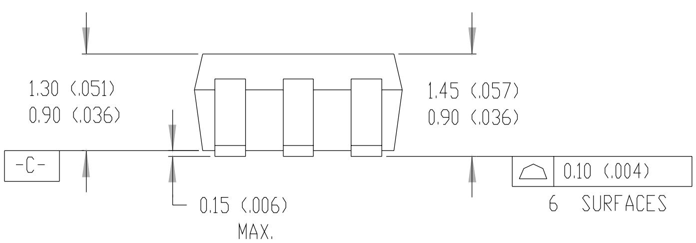


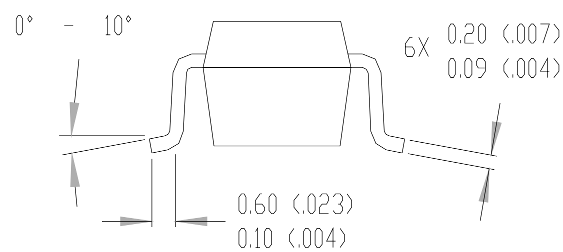




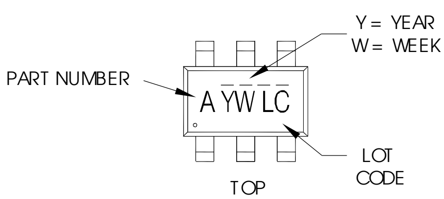
NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).





TSOP-6 Part Marking Information



PART NUMBER CODE REFERENCE:

A = SI3443DV
B = IRF5800
C = IRF5850
D = IRF5851
E = IRF5852
F = IRF5801
G = IRF5803
H = IRF5804
I = IRF5805
J = IRF5806
K = IRF5810
N = IRF5802
O = IRLTS6342TRPBF
P = IRFTS8342TRPBF
R = IRFTS9342TRPBF
S = IRLTS2242TRPBF

Note: A line above the work week (as shown here) indicates Lead-Free.

W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

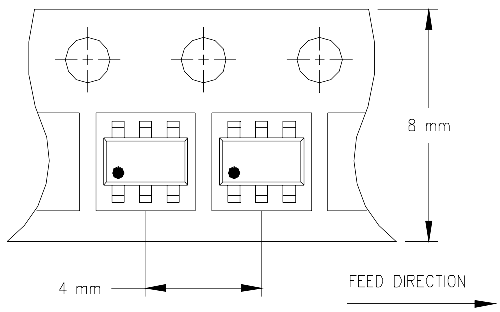
YEAR	Y	WORK WEEK	W
2001	1	01	A
2002	2	02	B
2003	3	03	C
2004	4	04	D
2005	5		
2006	6	↓	↓
2007	7		
2008	8		
2009	9		
2010	0	24	X
		25	Y
		26	Z

W = (27-52) IF PRECEDED BY A LETTER

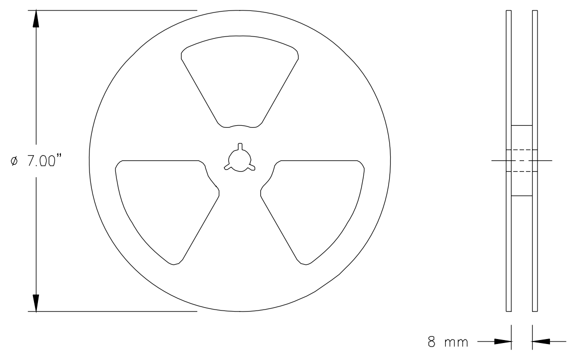
YEAR	Y	WORK WEEK	W
2001	A	27	A
2002	B	28	B
2003	C	29	C
2004	D	30	D
2005	E		
2006	F	↓	↓
2007	G		
2008	H		
2009	J		
2010	K	50	X
		51	Y
		52	Z

Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

TSOP-6 Tape & Reel Information



NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:
1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Qualification information†

Qualification level	Consumer†† (per JEDEC JESD47F ††† guidelines)	
Moisture Sensitivity Level	TSOP-6	MSL1 (per JEDEC J-STD-020D†††)
RoHS compliant	Yes	

† Qualification standards can be found at International Rectifier's web site http://www.irf.com/product-info/reliability

†† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information: http://www.irf.com/whoto-call/salesrep/

††† Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.

International
IOR Rectifier

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Visit us at www.irf.com for sales contact information.09/2011

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